

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC8102xxxx7R-G
Typical Mass: 1 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.114	Silicon	114200	7440-21-3
	-	Arsenic	13	7440-38-2
Lead pad	0.239	Nickel	239300	7440-02-0
	0.002	Gold	1500	7440-57-5
Die attach	0.009	Silica	8800	—
	0.004	Silicone	4000	—
	0.003	Bisphenol A, diglycidyl ether	3200	1675-54-3
Bonding wire	0.047	Gold	47300	7440-57-5
Resin	0.509	Silica	509000	60676-86-0
	0.029	Epoxy Resin	29100	—
	0.026	Phenol Resin	26200	—
	0.017	Metal Hydroxide	17500	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."